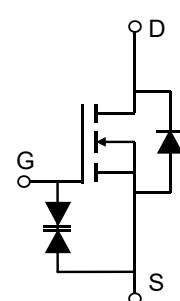


## Description

### Features

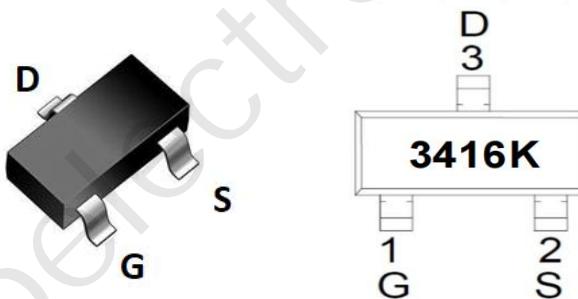
- 20V, 6A
- $R_{DS(ON)}$  Typ = 13mΩ @  $V_{GS}$  = 4.5V
- $R_{DS(ON)}$  Typ = 18mΩ @  $V_{GS}$  = 2.5V
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free
- ESD Protected: 2KV



Schematic Diagram

### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMLTU3416K	3416K	SOT-23	TAPING	13"	3000	120000

### Absolute Maximum Ratings (@ $T_J$ = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	20	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 10$	V
$I_D$	Continuous Drain Current $T_A = 25^\circ\text{C}$	6	A
	$T_A = 100^\circ\text{C}$	4	A
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	24	A
$P_D$	Power Dissipation $T_A = 25^\circ\text{C}$	1.25	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(2)</sup>	100	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

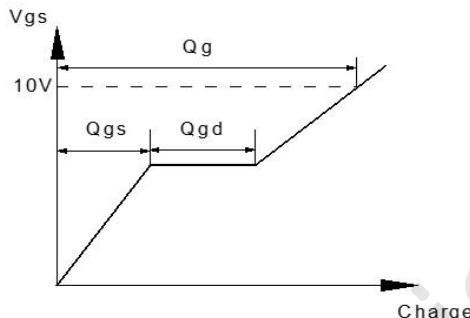
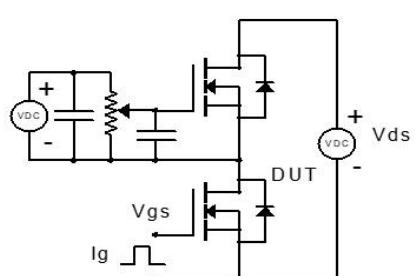
**Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±10V	-	-	±10	μA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4	0.65	1.0	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A	-	13	18	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 2A	-	18	23	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance		-	538	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 10V, f = 1MHz	-	115	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	104	-	pF
Q <sub>g</sub>	Total Gate Charge		-	8	-	nC
Q <sub>gs</sub>	Gate Source Charge	V <sub>GS</sub> = 0 to 4.5V V <sub>DS</sub> = 10V, I <sub>D</sub> = 6A	-	2	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	3	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime		-	1.2	-	ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>GS</sub> = 4.5V, V <sub>DD</sub> = 10V	-	2.4	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime	I <sub>D</sub> = 6A, R <sub>GEN</sub> = 3Ω	-	22	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	7	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	6	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	24	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 6A	-	-	1.2	V

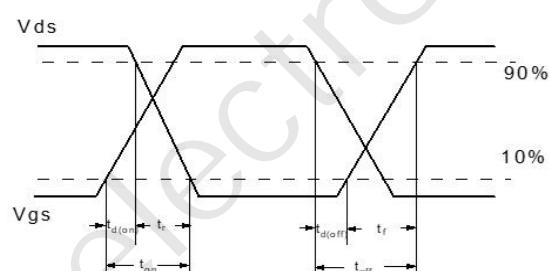
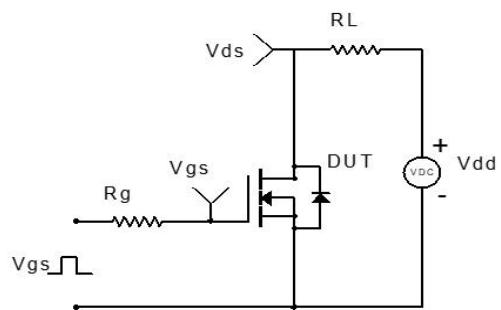
Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. R<sub>θJA</sub> is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

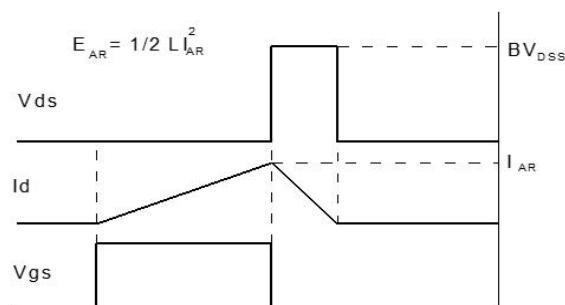
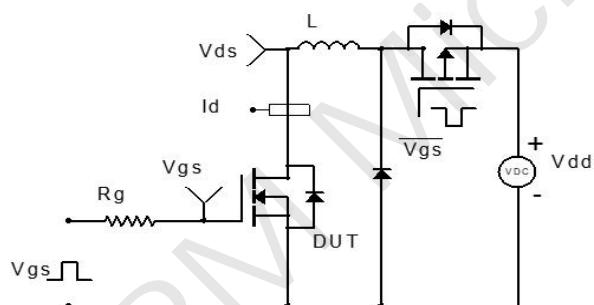
## Test Circuit



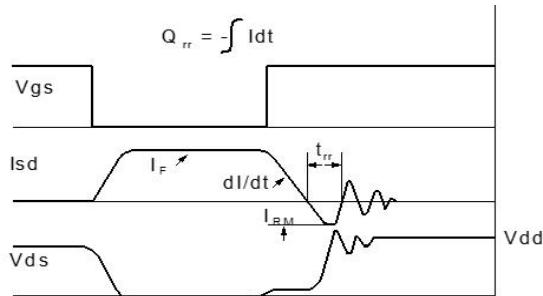
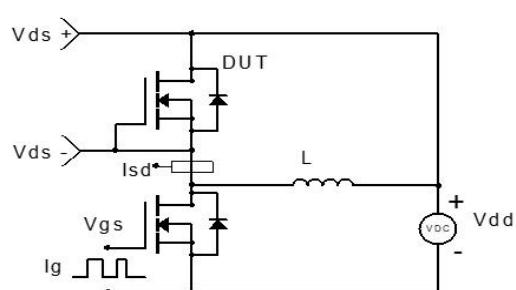
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

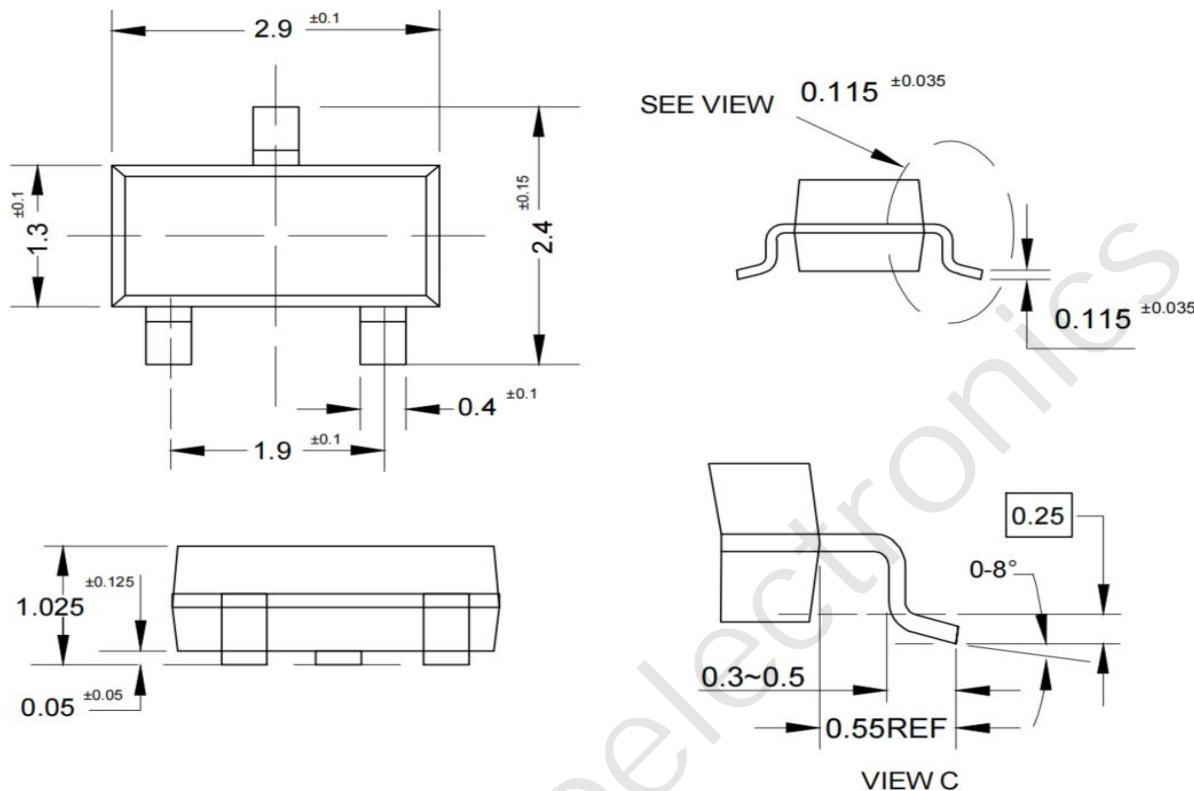


**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

## Package Mechanical Data(SOT-23)



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